PRELIMINARY

Integrated
Circuit
Systems, Inc.

ICS843011C

FEMTOCLOCKS™ CRYSTAL-TO-3.3V LVPECL CLOCK GENERATOR

GENERAL DESCRIPTION

ICS HiPerClockS™

The ICS843011C is a Fibre Channel Clock Generator and a member of the HiPerClocks™ family of high performance devices from ICS. The ICS843011C uses a 26.5625MHz crystal to synthesize 106.25MHz or a 25MHz crystal to synthesize 100MHz. The ICS843011C has excellent <1ps phase jitter performance, over the 637kHz – 10MHz integration range. The ICS843011C is packaged in a small 8-pin TSSOP, making it ideal for use in systems with limited board space.

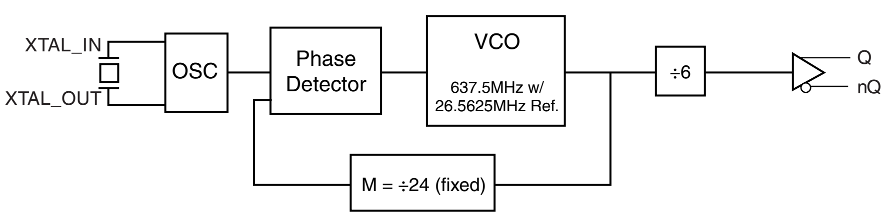
FEATURES

- One differential 3.3V LVPECL output
- Crystal oscillator interface designed for 26.5625MHz 18pF parallel resonant crystal
- Output frequency: 106.25MHz or 100MHz
- VCO range: 560MHz - 680MHz
- RMS phase jitter @ 100MHz, using a 25MHz crystal (637kHz - 10MHz): 0.29ps (typical)
- 3.3V operating supply
- -40°C to 85°C ambient operating temperature
- Available in both standard and lead-free RoHS compliant packages

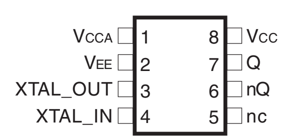
FREQUENCY TABLE

Crystal (MHz)	Output Frequency (MHz)
26.5625	106.25
25	100

BLOCK DIAGRAM



PIN ASSIGNMENT



ICS843011C

8-Lead TSSOP
4.40mm x 3.0mm x 0.925mm package body
G Package
Top View

The Preliminary Information presented herein represents a product in prototyping or pre-production. The noted characteristics are based on initial product characterization. Integrated Circuit Systems, Incorporated (ICS) reserves the right to change any circuitry or specifications without notice.

TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1	V_{CCA}	Power		Analog supply pin.
2	V_{EE}	Power		Negative supply pin.
3, 4	XTAL_OUT, XTAL_IN	Input		Crystal oscillator interface. XTAL_IN is the input, XTAL_OUT is the output.
5	nc	Unused		No connect.
6, 7	nQ, Q	Output		Differential clock outputs. LVPECL interface levels.
8	V_{CC}	Power		Core supply pin.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			4		pF

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{CC}	4.6V
Inputs, V_I	-0.5V to V_{CC} + 0.5V
Outputs, I_O	
Continuous Current	50mA
Surge Current	100mA
Package Thermal Impedance, θ_{JA}	101.7°C/W (0 mps)
Storage Temperature, T_{STG}	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 3A. POWER SUPPLY DC CHARACTERISTICS, V_{CC} = 3.3V±5%, TA = -40°C TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{CC}	Core Supply Voltage		3.135	3.3	3.465	V
V_{CCA}	Analog Supply Voltage		3.135	3.3	3.465	V
I_{CCA}	Analog Supply Current	included in I_{EE}		10		mA
I_{EE}	Power Supply Current			68		mA

TABLE 3B. LVPECL DC CHARACTERISTICS, V_{CC} = 3.3V±5%, TA = -40°C TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OH}	Output High Voltage; NOTE 1		V_{CC} - 1.4		V_{CC} - 0.9	V
V_{OL}	Output Low Voltage; NOTE 1		V_{CC} - 2.0		V_{CC} - 1.7	V
V_{SWING}	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with 50Ω to V_{CC} - 2V.

TABLE 4. CRYSTAL CHARACTERISTICS

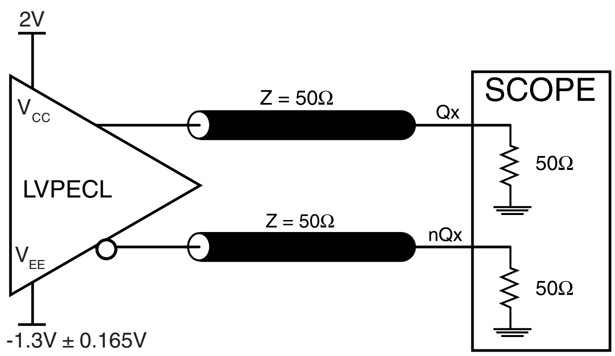
Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation			Fundamental		
Frequency		25		26.5625	MHz
Equivalent Series Resistance (ESR)				50	Ω
Shunt Capacitance				7	pF

TABLE 5. AC CHARACTERISTICS, V_{CC} = 3.3V±5%, TA = -40°C TO 85°C

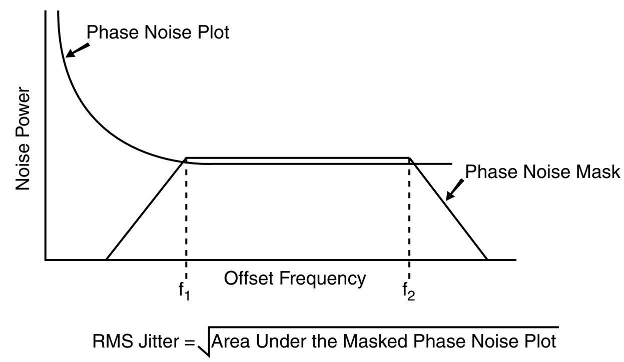
Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
F_{OUT}	Output Frequency		93.33		113.33	MHz
tjit(Ø)	RMS Phase Jitter (Random); NOTE 1	106.25MHz; Integration Range: 637kHz - 10MHz		0.29		ps
		100MHz; Integration Range: 637kHz - 10MHz		0.29		ps
t_R / t_F	Output Rise/Fall Time	20% to 80%		400		ps
odc	Output Duty Cycle			50		%

NOTE 1: Please refer to the Phase Noise Plot.

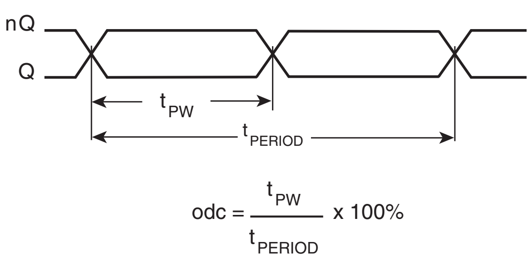
PARAMETER MEASUREMENT INFORMATION



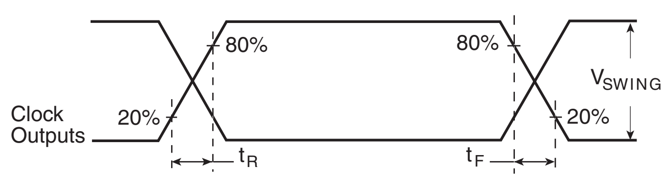
3.3V OUTPUT LOAD AC TEST CIRCUIT



RMS PHASE JITTER



OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD



OUTPUT RISE/FALL TIME

APPLICATION INFORMATION

POWER SUPPLY FILTERING TECHNIQUES

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. The ICS843011C provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. V_{CC} and V_{CCA} should be individually connected to the power supply plane through vias, and bypass capacitors should be used for each pin. To achieve optimum jitter performance, power supply isolation is required. *Figure 1* illustrates how a 10Ω resistor along with a 10µF and a .01µF bypass capacitor should be connected to each V_{CCA} pin.

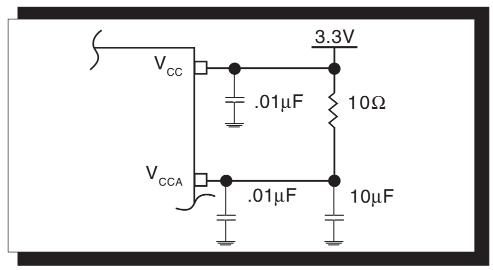


FIGURE 1. POWER SUPPLY FILTERING

CRYSTAL INPUT INTERFACE

The ICS843011C has been characterized with 18pF parallel resonant crystals. The capacitor values, C1 and C2, shown in *Figure 2* below were determined using a 26.5625MHz, 18pF parallel resonant crystal and were chosen to minimize the ppm error. The optimum C1 and C2 values can be slightly adjusted for different board layouts.

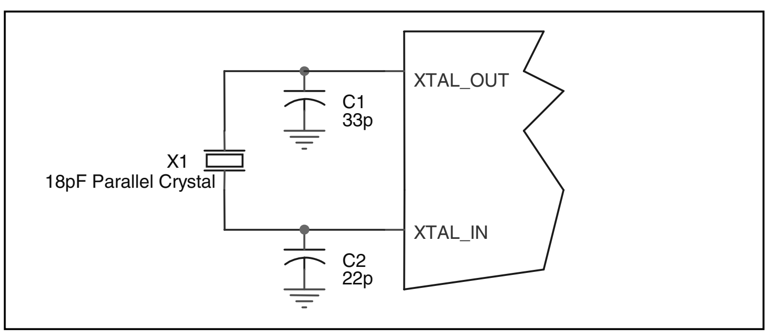


Figure 2. CRYSTAL INPUT INTERFACE

APPLICATION SCHEMATIC

Figure 3A shows a schematic example of the ICS843011C. An example of LVEPCL termination is shown in this schematic. Additional LVPECL termination approaches are shown in the LVPECL Termination Application Note. In this example, an 18 pF parallel resonant 26.5625MHz crystal is used for generating 106.25MHz output frequency. The C1 = 27pF and C2 = 33pF are recommended for frequency accuracy. For different board layout, the C1 and C2 values may be slightly adjusted for optimizing frequency accuracy.

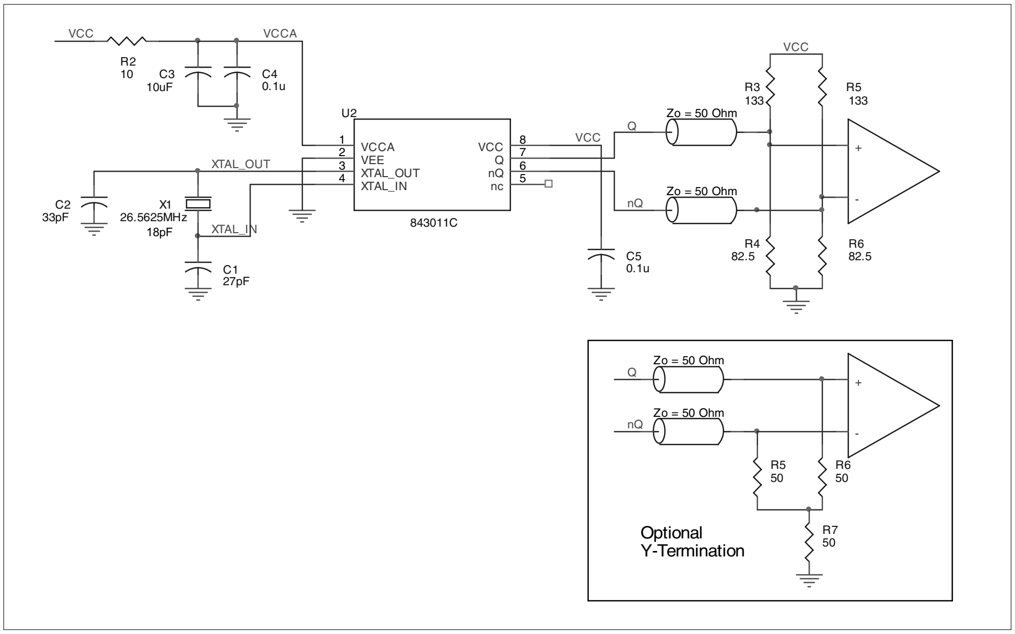


FIGURE 3A. ICS843011C SCHEMATIC EXAMPLE

PC BOARD LAYOUT EXAMPLE

Figure 3B shows an example of ICS843011C P.C. board layout. The crystal X1 footprint shown in this example allows installation of either surface mount HC49S or through-hole HC49 package. The footprints of other components in this example are listed in the *Table 6.* There should be at least one decoupling capacitor per power pin. The decoupling capacitors should be located as close as possible to the power pins. The layout assumes that the board has clean analog power ground plane.

TABLE 6. FOOTPRINT TABLE

Reference	Size
C1, C2	0402
C3	0805
C4, C5	0603
R2	0603

NOTE: Table 6, lists component sizes shown in this layout example.

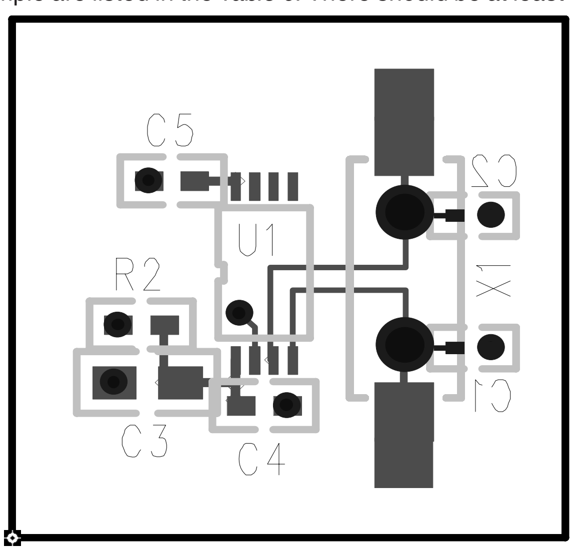


FIGURE 3B. ICS843011 PC BOARD LAYOUT EXAMPLE

POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS843011C. Equations and example calculations are also provided.

1. Power Dissipation.
The total power dissipation for the ICS843011C is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for V_{CC} = 3.3V + 5% = 3.465V, which gives worst case results.
NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)$_{MAX}$ = V_{CC_MAX} * I_{EE_MAX} = 3.465V * 68mA = **235.6mW**
- Power (outputs)$_{MAX}$ = **30mW/Loaded Output pair**

Total Power $_{\_MAX}$ (3.465V, with all outputs switching) = 235.6mW + 30mW = **265.6mW**

2. Junction Temperature.
Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for Tj is as follows: Tj = θ_{JA} * Pd_total + T_A

Tj = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming a moderate air flow of 1 meter per second and a multi-layer board, the appropriate value is 90.5°C/W per Table 7 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:
85°C + 0.266W * 90.5°C/W = 109.1°C. This is well below the limit of 125°C.

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

TABLE 7. THERMAL RESISTANCE θ_{JA} FOR 8-PIN TSSOP, FORCED CONVECTION

θ_{JA} by Velocity (Meters per Second)			
	0	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	101.7°C/W	90.5°C/W	89.8°C/W

3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in *Figure 4.*

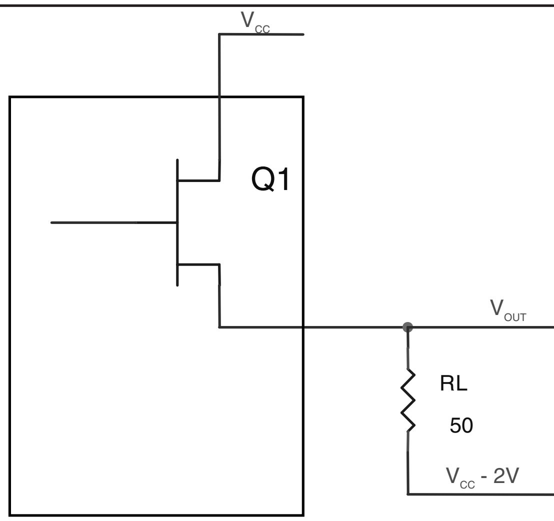


FIGURE 4. LVPECL DRIVER CIRCUIT AND TERMINATION

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of V_{CC} - 2V.

- For logic high, $V_{OUT} = V_{OH\_MAX} = \mathbf{V_{CC\_MAX} – 0.9V}$

  $(V_{CCO\_MAX} - V_{OH\_MAX}) = \mathbf{0.9V}$

- For logic low, $V_{OUT} = V_{OL\_MAX} = \mathbf{V_{CC\_MAX} – 1.7V}$

  $(V_{CCO\_MAX} - V_{OL\_MAX}) = \mathbf{1.7V}$

Pd_H is power dissipation when the output drives high.
Pd_L is the power dissipation when the output drives low.

$Pd\_H = [(V_{OH\_MAX} – (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OH\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) =$
$[(2V - 0.9V)/50\Omega] * 0.9V = \mathbf{19.8mW}$

$Pd\_L = [(V_{OL\_MAX} – (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OL\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) =$
$[(2V - 1.7V)/50\Omega] * 1.7V = \mathbf{10.2mW}$

Total Power Dissipation per output pair = Pd_H + Pd_L = **30mW**

RELIABILITY INFORMATION

TABLE 8. θ_{JA} VS. AIR FLOW TABLE FOR 8 LEAD TSSOP

θ_{JA} by Velocity (Meters per Second)			
	0	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	101.7°C/W	90.5°C/W	89.8°C/W

TRANSISTOR COUNT

The transistor count for ICS843011C is: 2436

PACKAGE OUTLINE - G SUFFIX FOR 8 LEAD TSSOP

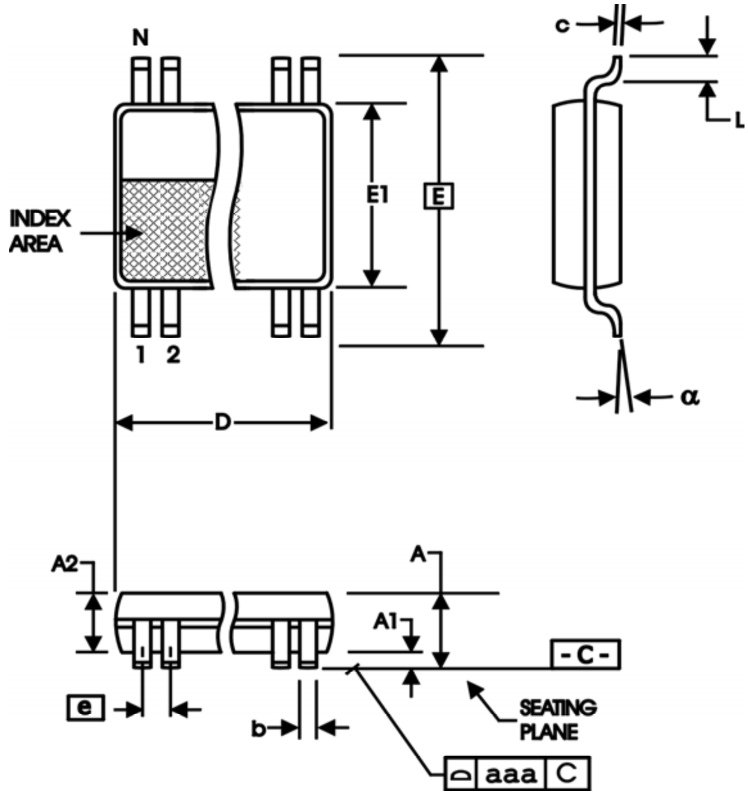


TABLE 9. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	Minimum	Maximum
N	8	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	2.90	3.10
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
α	0°	8°
aaa	--	0.10

Reference Document: JEDEC Publication 95, MO-153

TABLE 10. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS843011CG	3011C	8 lead TSSOP	tube	-40°C to 85°C
ICS843011CGT	3011C	8 lead TSSOP	2500 tape & reel	-40°C to 85°C
ICS843011CGLF	TBD	8 lead "Lead-Free" TSSOP	tube	-40°C to 85°C
ICS843011CGLFT	TBD	8 lead "Lead-Free" TSSOP	2500 tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF suffix to the part number are the Pb-Free configuration and are RoHS compliant.